

Micro-/Nanotechnology Facility

Our state-of-the-art micro- and nanotechnology fabrication facility has the equipment and infrastructure needed for lithography, etching, diffusion, wafer bonding, and thin-film deposition and vacuum techniques such as metal evaporation and sputtering, plasma enhanced chemical vapor deposition (PECVD), and low-pressure chemical vapor deposition (LPCVD). The facility houses over 6000 square feet of Class 10–1000 clean rooms for micromachining, silicon microelectronics, III–V semiconductor optoelectronics, and guided-wave photonics



Class 100 cleanroom